



Exceptional service in the national interest

Ex-Situ, Surface and Bulk Investigations of Defluxing Chemistry Effects on Solder Mask

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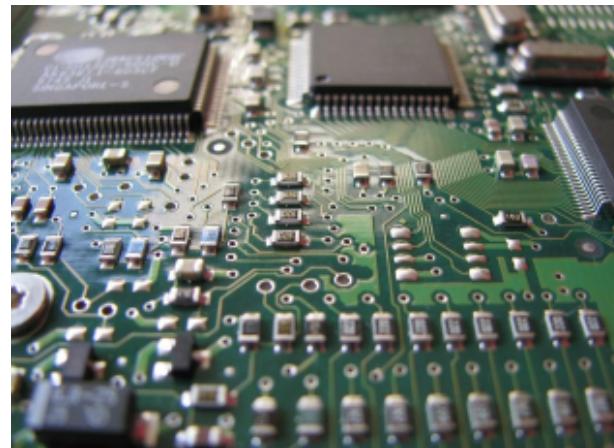
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Presented at AVS 2022

Pittsburgh, PA, USA

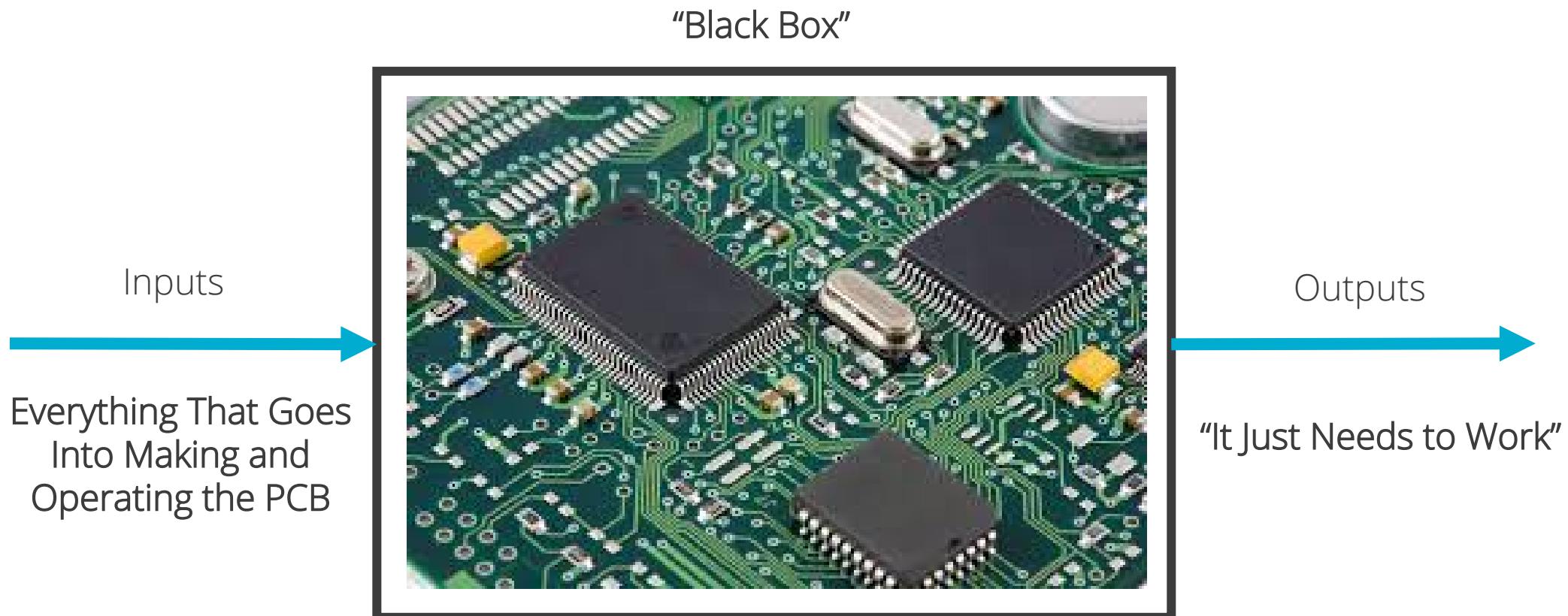


We Rely on Printed Circuit Boards (PCBs) For Everything





It's Easy to Treat PCBs As a Black Box





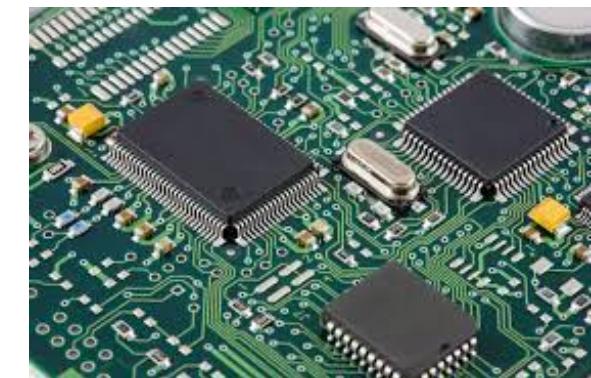
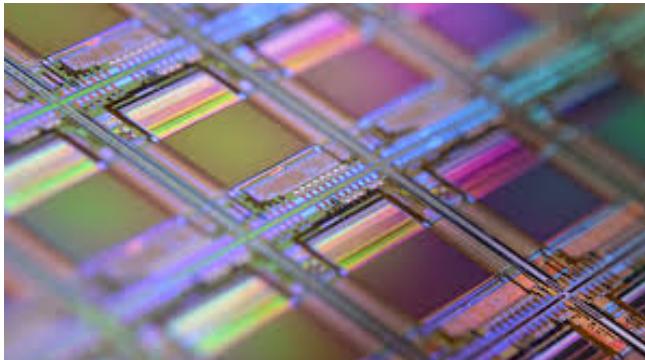
PCBs Materials Complexity is a Compounding Problem

SCALE

Nano -> Micro

Micro -> Milli

Milli -> Macro



Materials

$10^0 - 10^1$

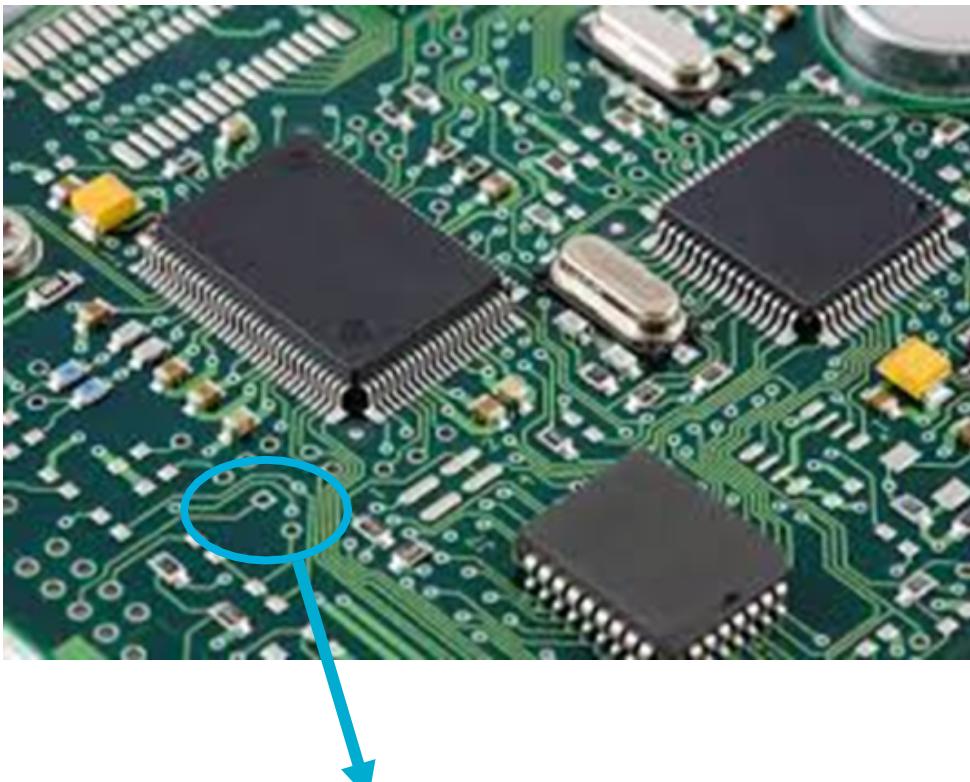
$10^1 - 10^2$

$10^2 - 10^3+$

Solder Mask is a Heterogeneous Material

What is Solder Mask?

(Liquid-Photoimageable Variety, Most Common for SMT)

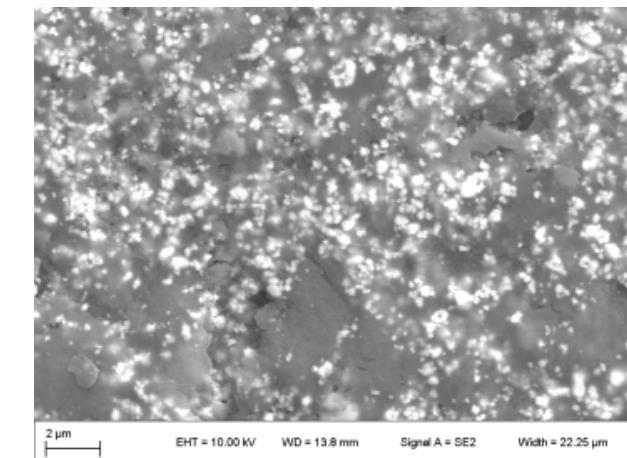


Solder Mask is all this green stuff

Solder Mask
Copper

Made up of:

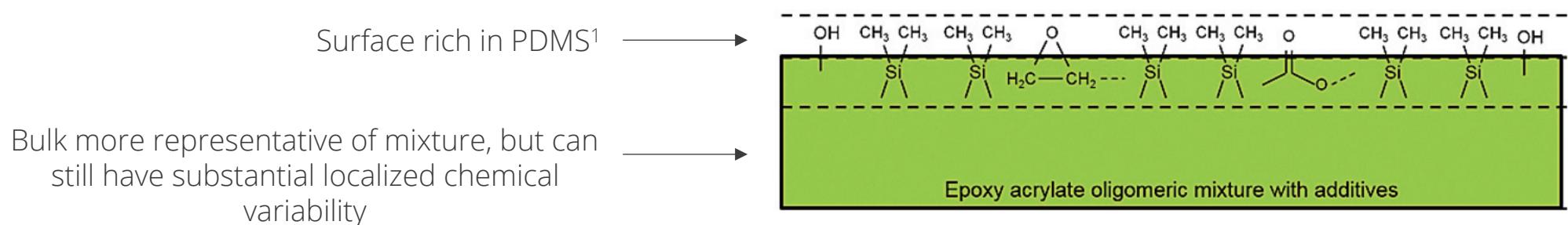
- Epoxy Acrylate Resin
- Hardener Chemistry
- Numerous Fillers and Additives
 - Quartz, SiO₂ for viscosity
 - Barium Sulfate for flame resistance
 - PDMS for optimal surface tension, spreading



SEM Image of LPI Solder Mask –
Taken @ Sandia National Labs

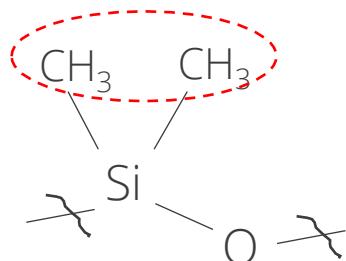
Heterogeneous Materials Behave Uniquely

Heterogeneous materials can have wildly different chemistries at a local level



Surface chemistry dictates materials' interaction with external environments

Polydimethylsiloxanes (PDMS)



Externally-oriented methyl groups make surfaces more hydrophobic (water hating)

This is good for reducing moisture uptake! Especially considering there is a negative linear relationship between moisture content and capacitance of solder mask material²

1) Hofmeister, C., et al., Materials Chemistry & Physics (2017) 185, 129

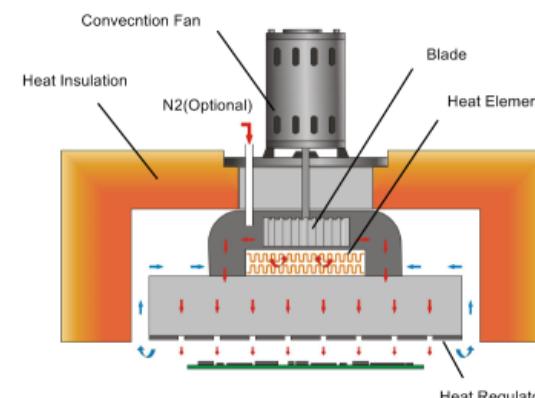
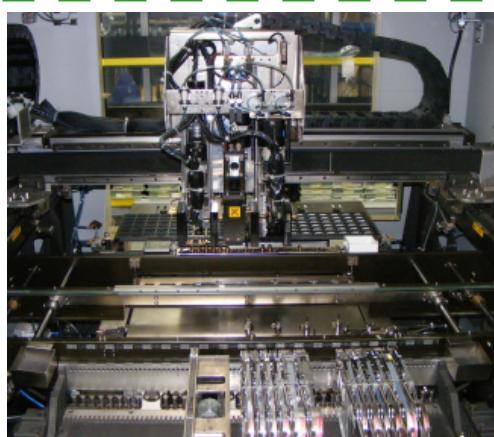
2) Pecht, M. G., et al., IEEE Transactions on Components Packaging Technologies (1999) 22 (1), 104



PCB Assembly – 10000 ft. Level

Lots of effort put here developing better metallurgy and methodology to advance [Moore's Law](#)

Yes, most PCBs are washed in AQUEOUS solutions!

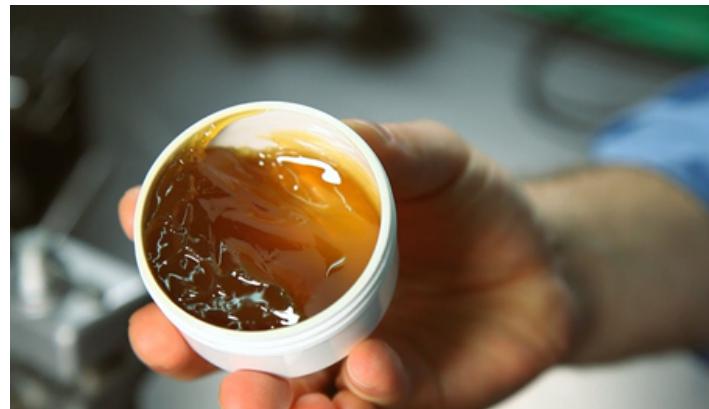




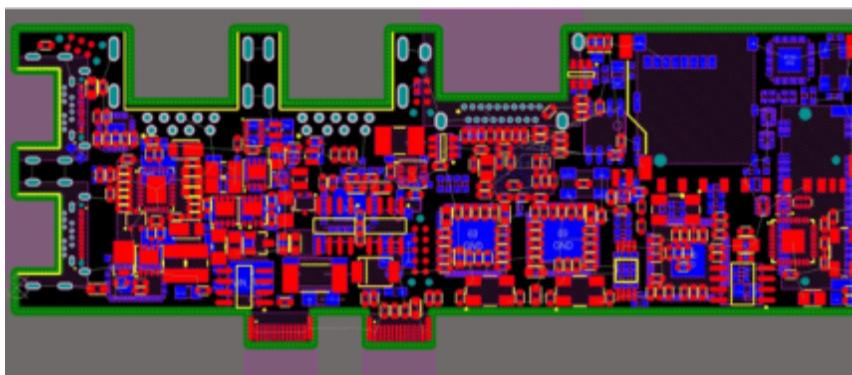
Modern Soldering Flux

What is flux? Five general chemical components:

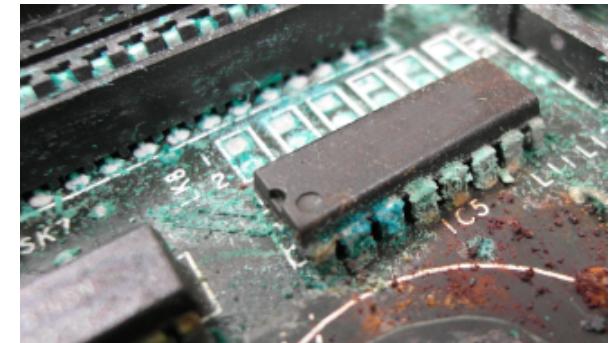
- Rosin
- Resin
- Activators
- Halides
- Surfactants



When we started shoving smaller and smaller devices together as densely as possible...



Corrosion!



Solution -
Swap Halides for Weak Organic Acid Activators

Consequences -

- pH of Flux Plummets
- Cleaning Chemistries Must Become Highly Alkaline to Counterbalance

Hypothesis

Increasing Alkalinity

~7

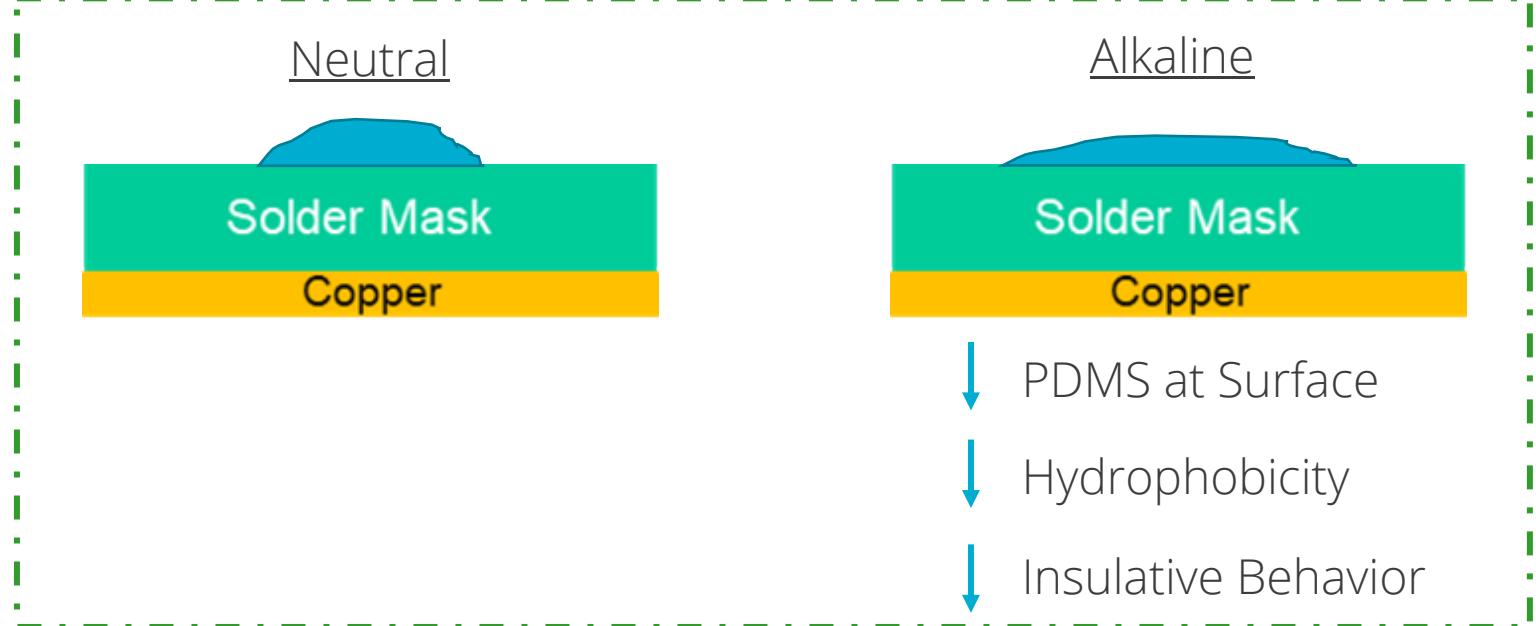
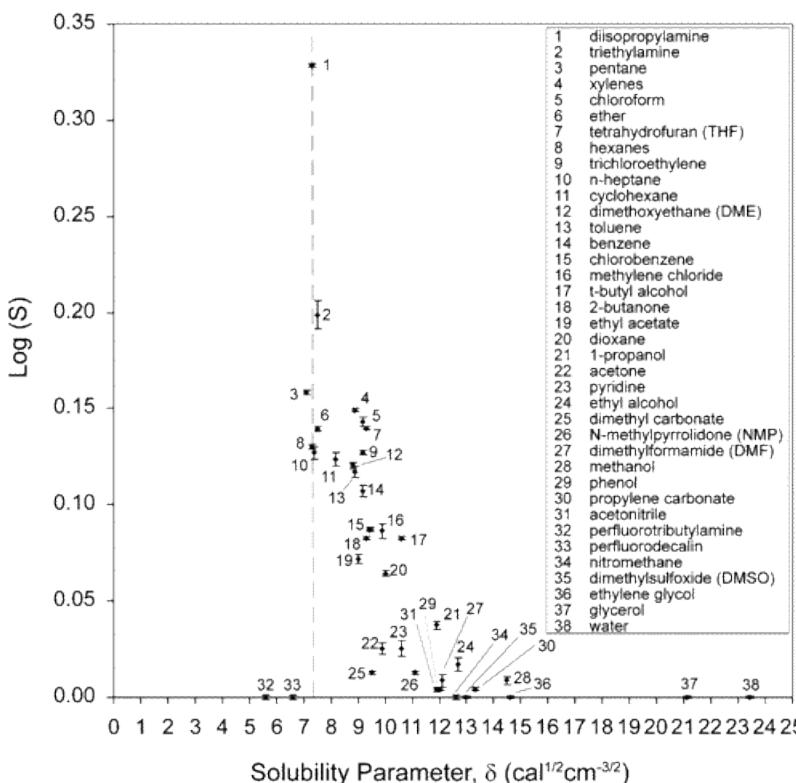
DI Water

~12

'pH Neutral'

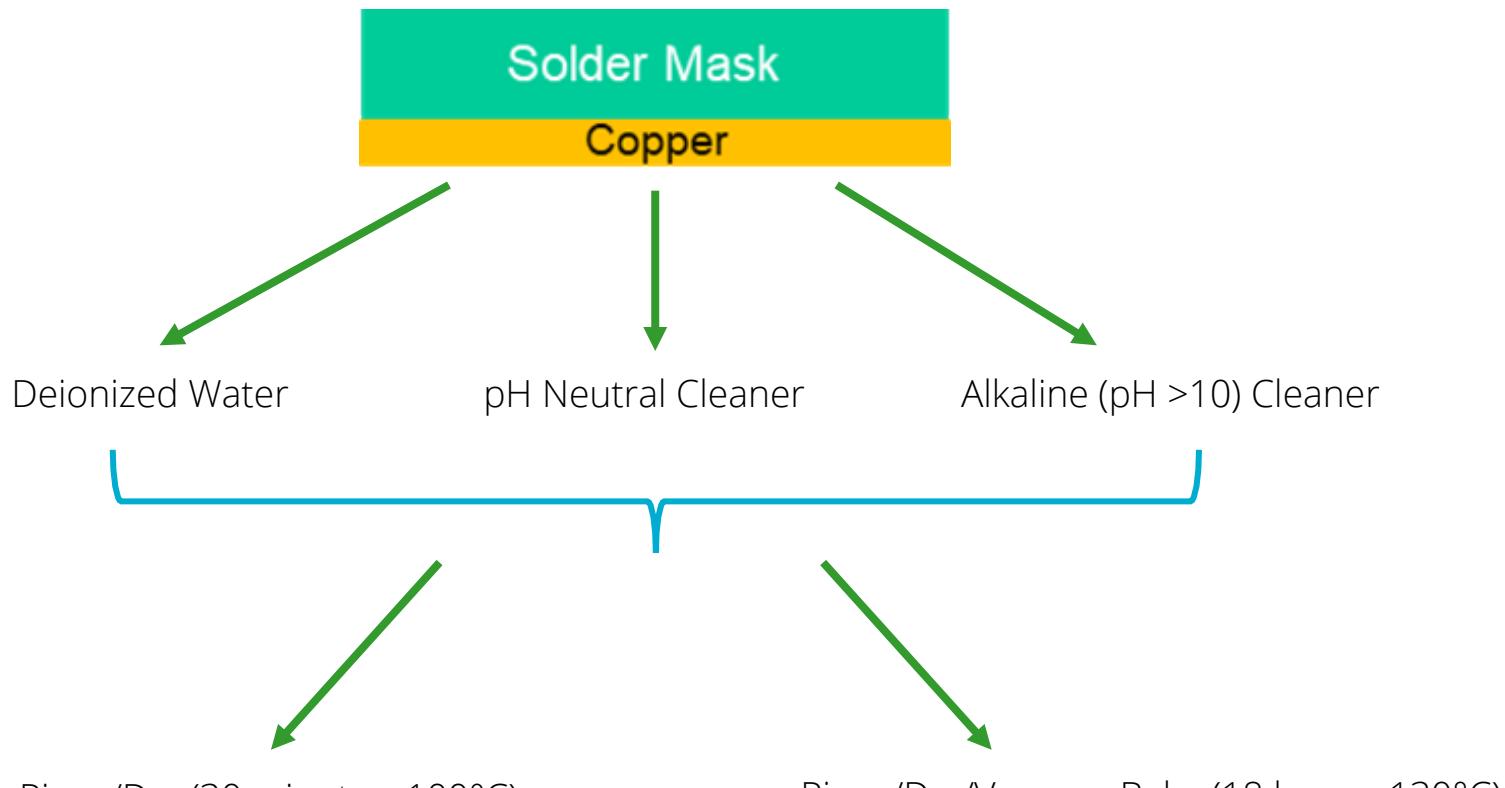
Alkaline

More alkaline chemistries will remove or modify the surface chemistry of the solder mask



Experimental Design

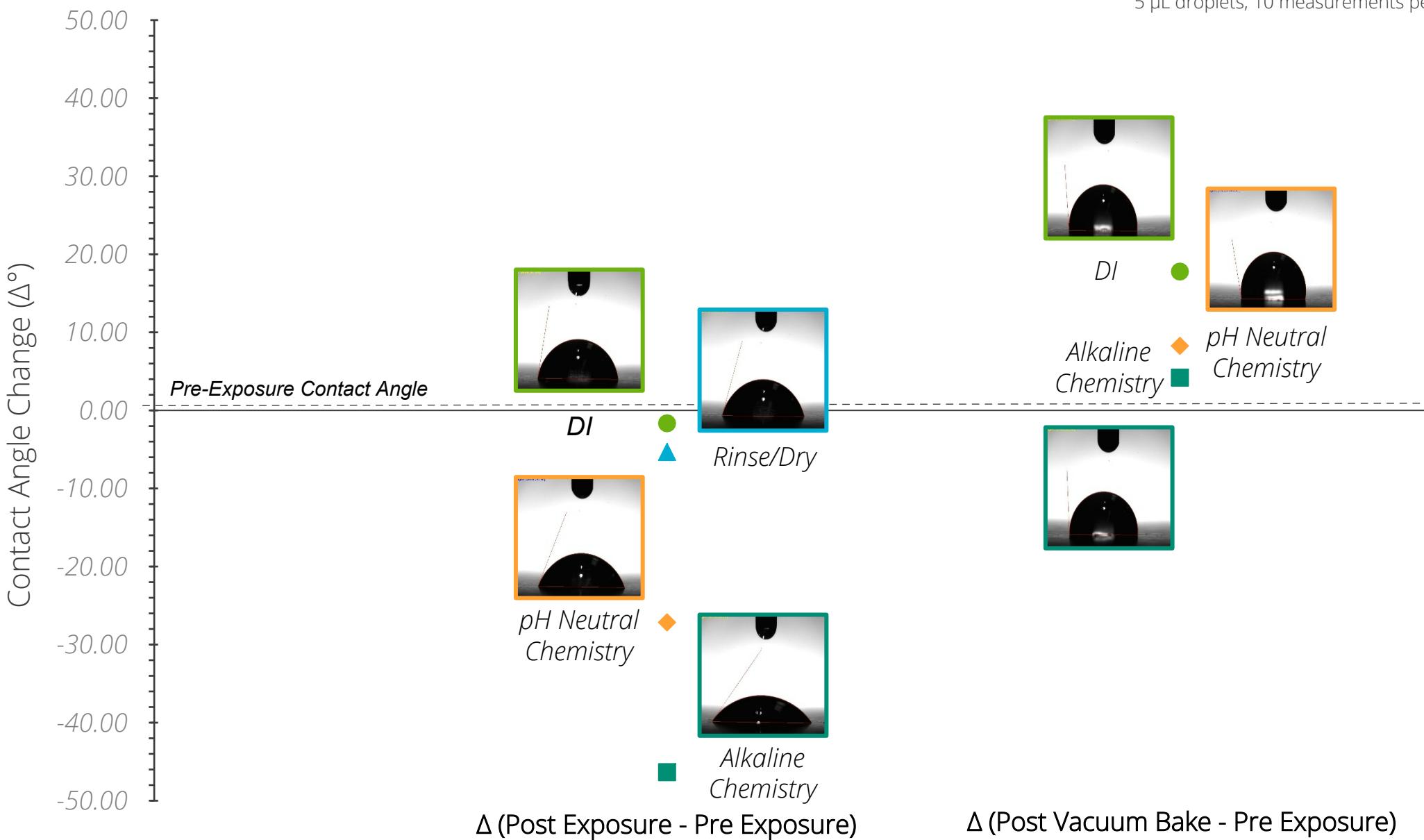
80°C for 80 minutes



Perform Analysis:

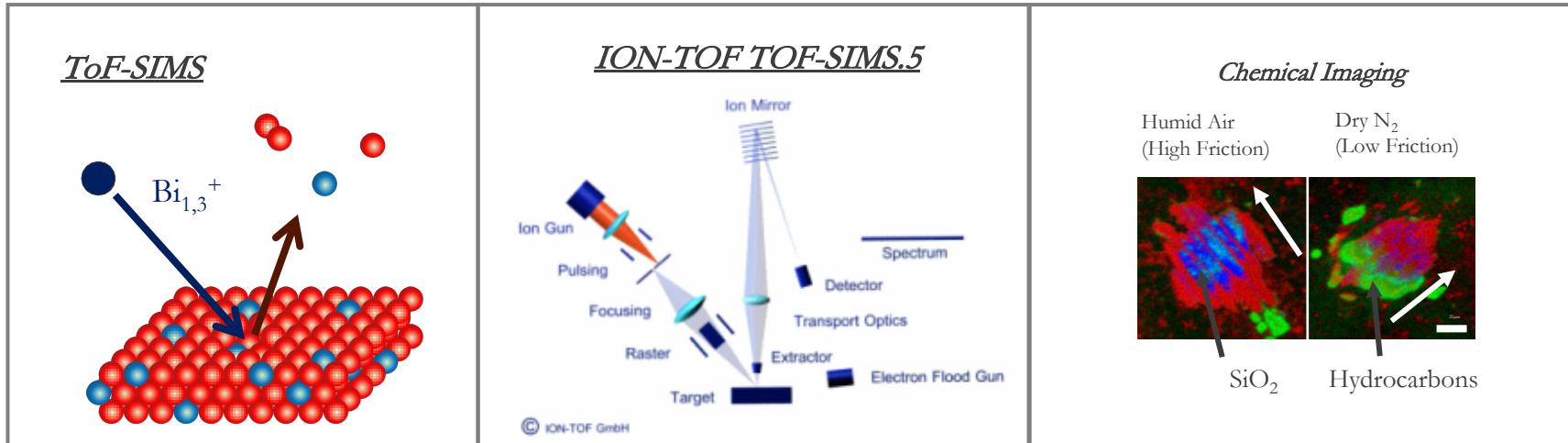
- Water Contact Angle
- Time-of-Flight SIMS
- X-Ray Photoelectron Spectroscopy
- Electrochemical Impedance Spectroscopy

Contact Angle Goniometry



Time of Flight Secondary Ion Mass Spectrometry

ToF-SIMS analyzes material ion fragments from ion bombardment

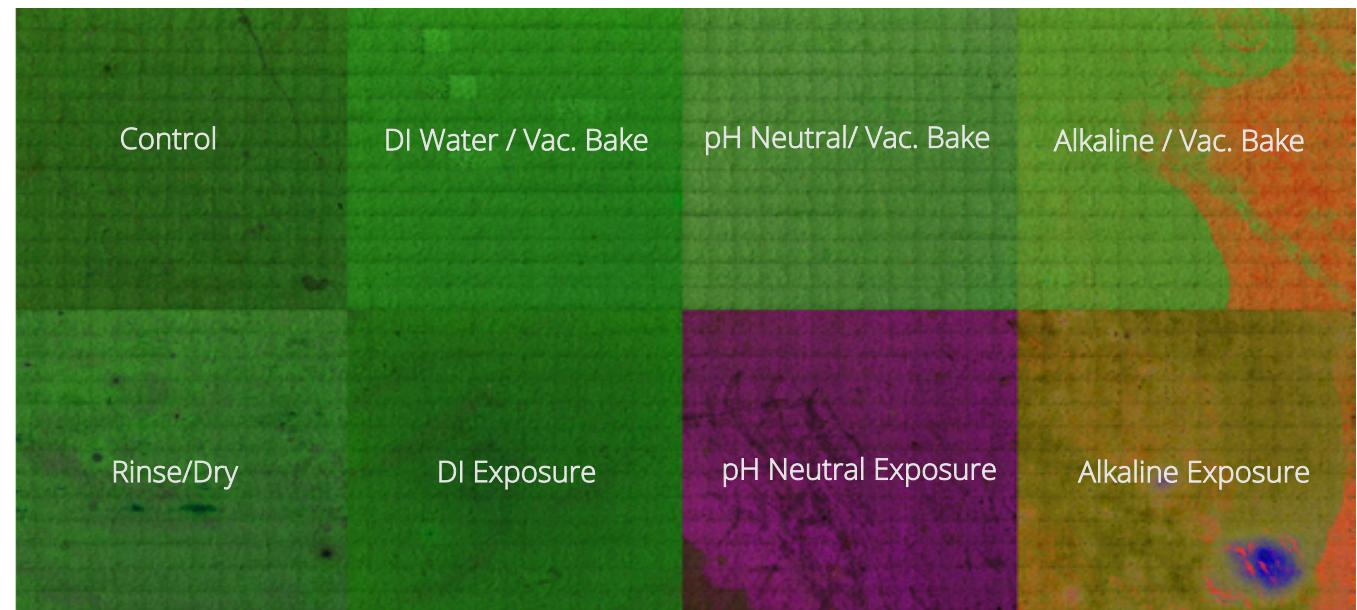


5x5mm² area 15x15 patches resulting in 255x255 pixels, 40 shots per pixel

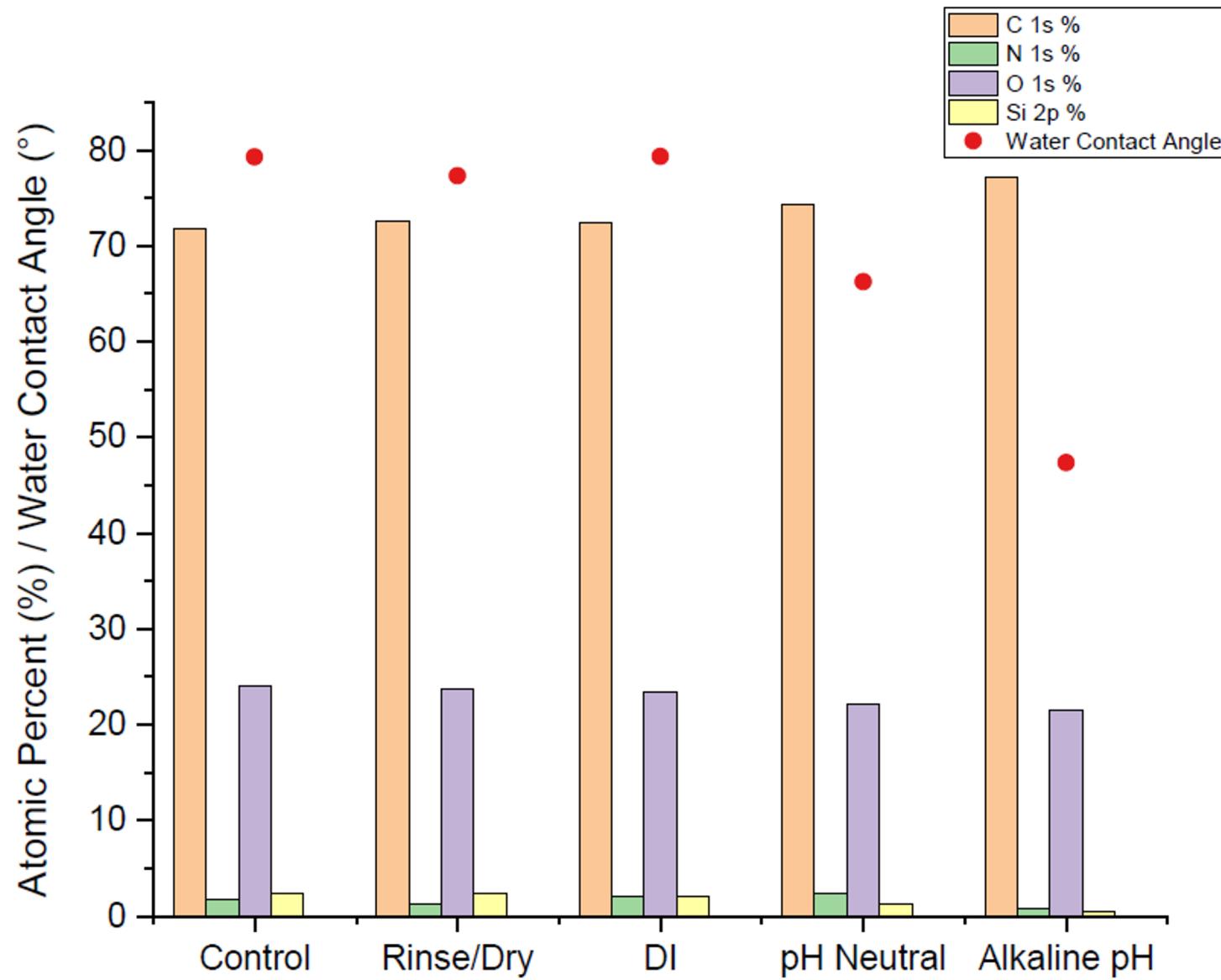
Green: Silicones

Magenta: Unique (pH neutral) organics

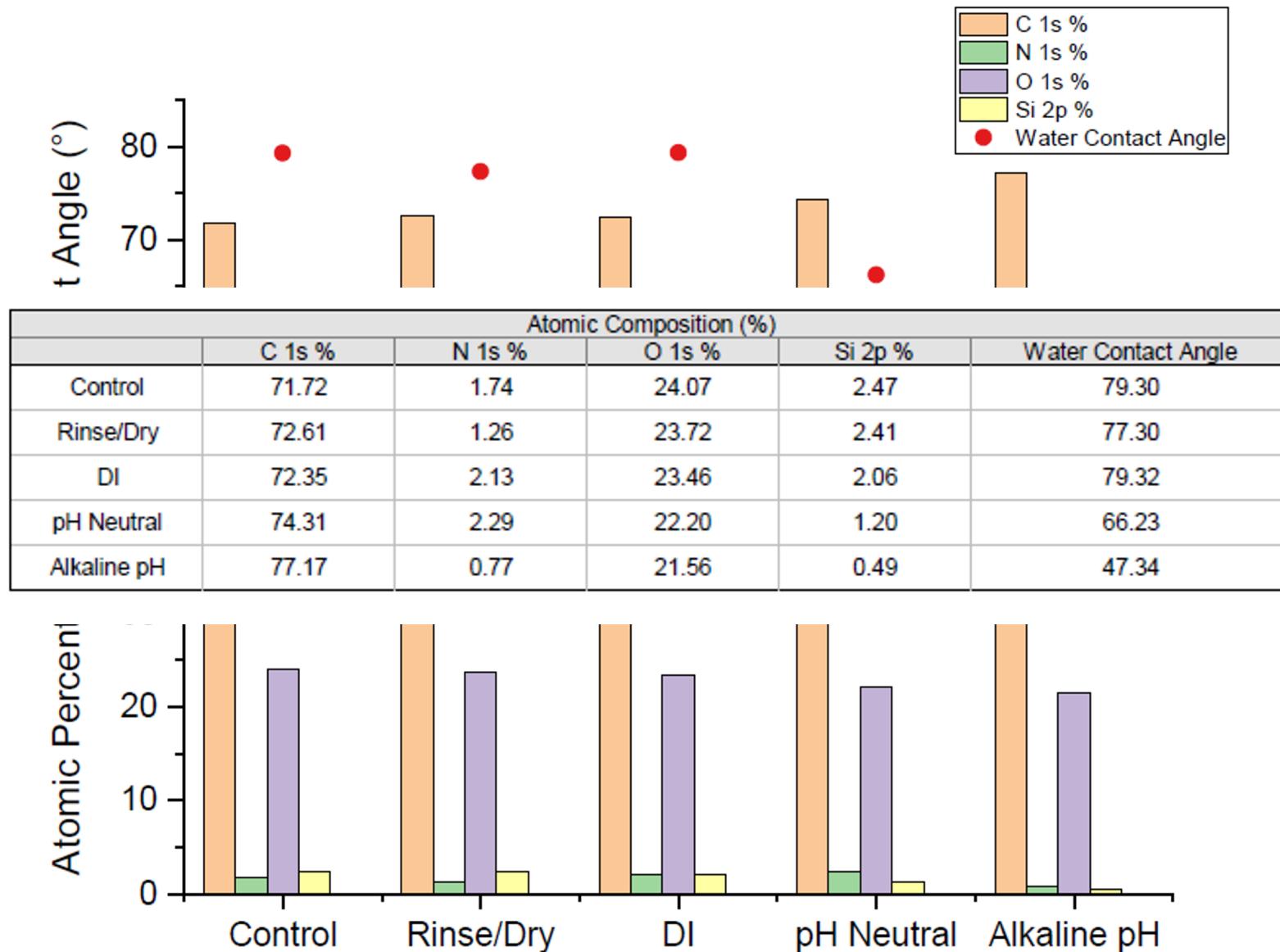
Yellow: Unique (Alkaline) organics



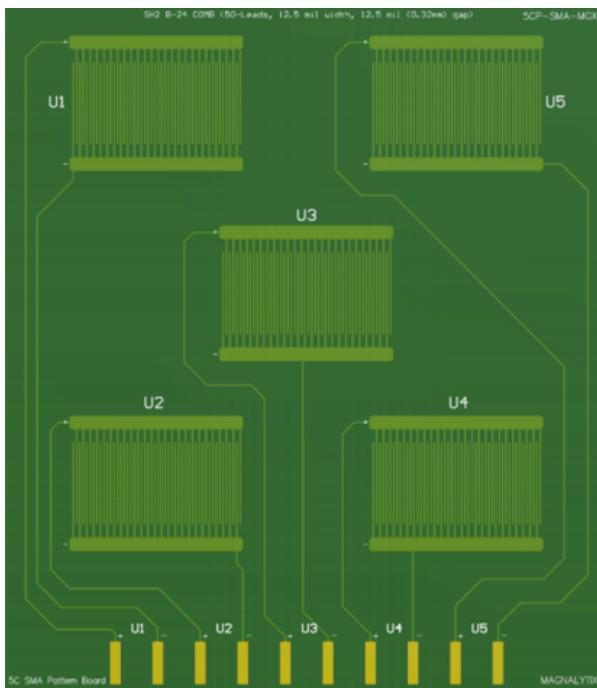
X-Ray Photoelectron Spectroscopy



X-Ray Photoelectron Spectroscopy



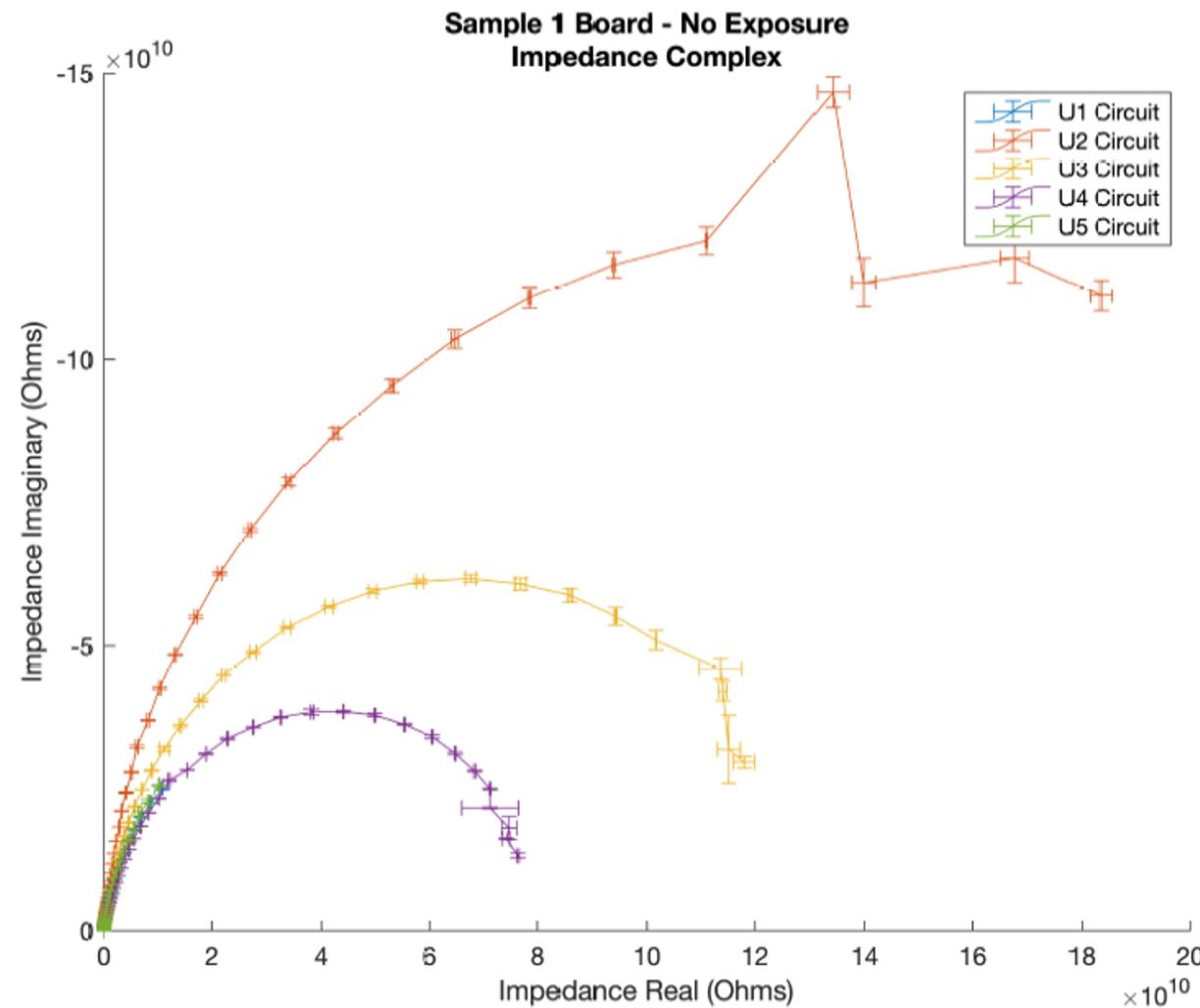
AC Electrochemical Impedance Spectroscopy



EIS Test Sample – 5 identical comb patterns

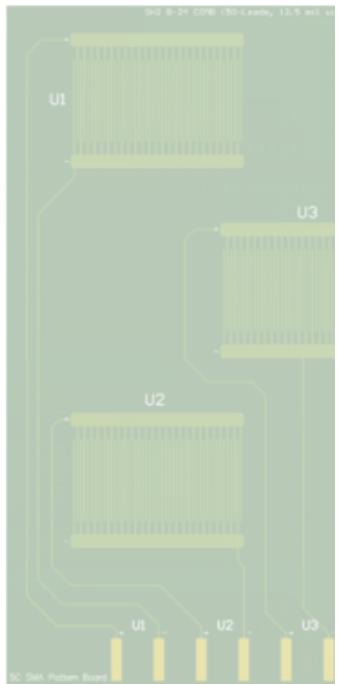


2D Profile of Surface Topography of Comb Section (Collected via Laser Scanning Confocal Microscopy)



AC Electrochemical Impedance Spectroscopy

Impedance Spectroscopy for Quality Testing of Interdigitated Circuits



EIS Test Sample – pattern



2D Profile of Surface Section (Collected via Laser Scanning Confocal Microscopy)

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Abstract—Electronic components are affected by several factors, some of which include temperature and relative humidity of the environment of operation. When fabricating multiple identical components, it is important to ensure all variables involved in the fabrication of each component are equal. Impedance spectroscopy as a tool holds potential in verifying whether components are identical to one another, as it can test a material's response using AC voltage throughout a range of frequencies. In this paper, impedance spectroscopy is used in quality testing two boards with interdigitated circuits fabricated at Sandia National Laboratory. Statistical methods are performed to share the referenceable numerical differences between the circuits on a board throughout the frequency range. It was found evident that significant differences existed between the circuits on a single board. Tests were also done at varying relative humidity levels to highlight its effect on circuit operations. Frequency and relative humidity were found to play a critical role in the behavior of the circuits.

Keywords—impedance, frequency, humidity, error, repeatability, reproducibility.

I. INTRODUCTION

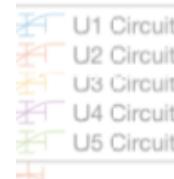
Impedance spectroscopy was used to characterize several solder masked circuit boards with interdigitated circuits fabricated at Sandia National Laboratory. Each circuit contained

response. Measurements were done under normal laboratory conditions of relative humidity and temperature to represent sample responses under easily repeatable conditions. Investigated are the similarities and differences of the uncoated non-exposed boards in terms of statistical relations between measurements of a single circuit and measurements of all five circuits on two different boards.

II. METHODS

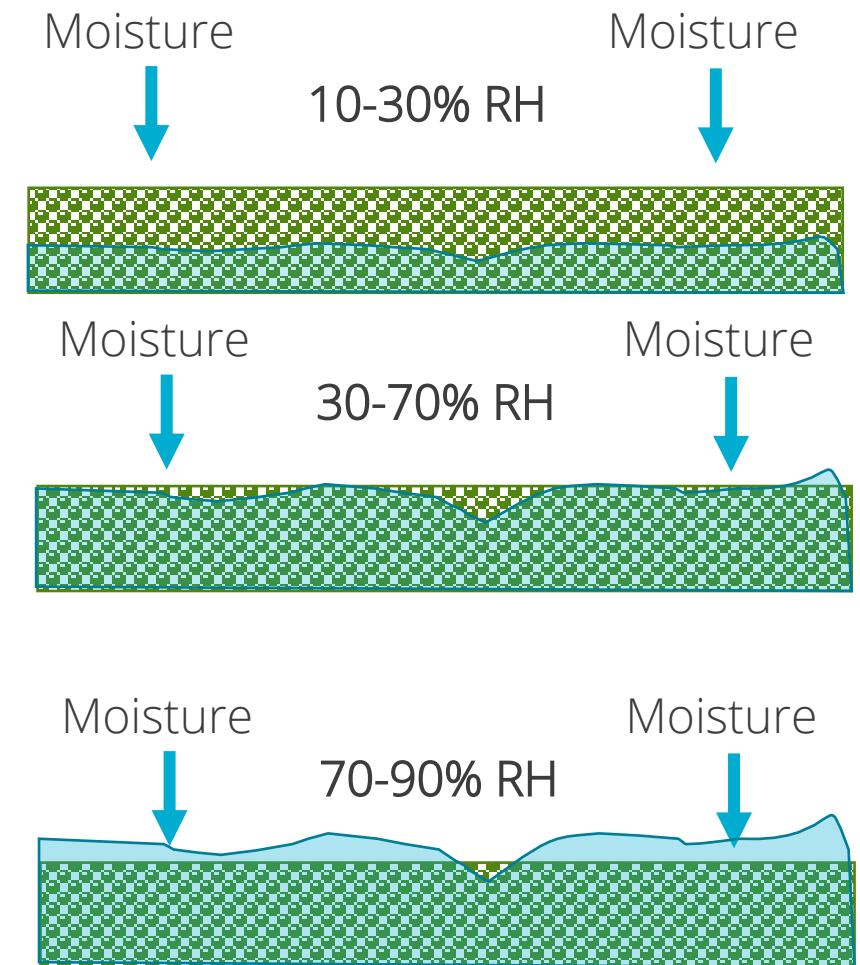
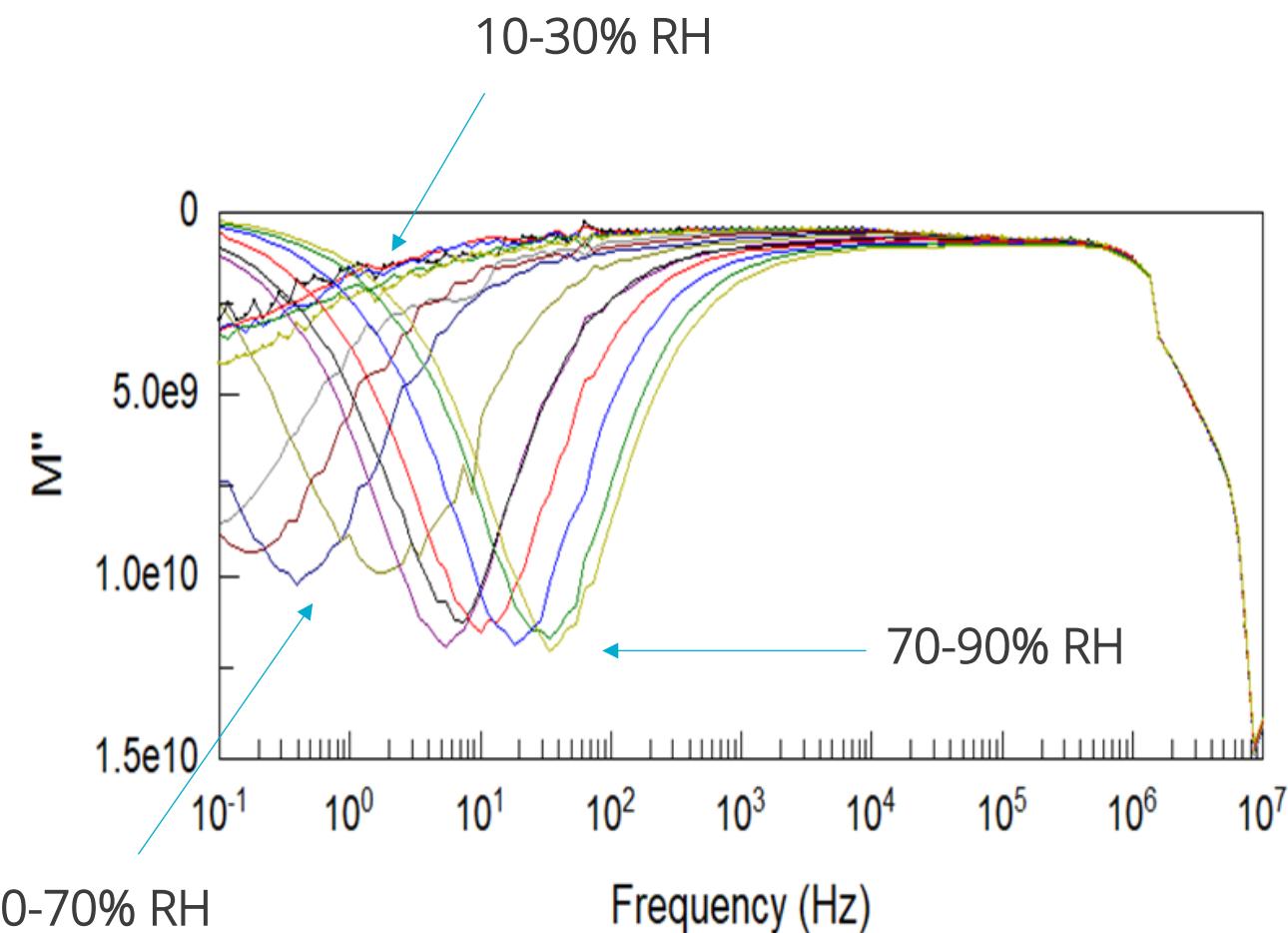
A. Impedance Spectroscopy

Impedance measurements were done using a Solartron SI 1260 and Solartron 1296 Dielectric Interface, operated using SMaRT Impedance Measurement software. Measurements were done for the five circuits on each board. Three runs or tests were performed per circuit to verify the impedance response being measured, which were further reviewed using ZView Impedance Software. One such measurement spectrum is depicted in Fig. 3 for Sample8 at circuit U2. Measurements were performed at an AC voltage of 500 mV through a frequency



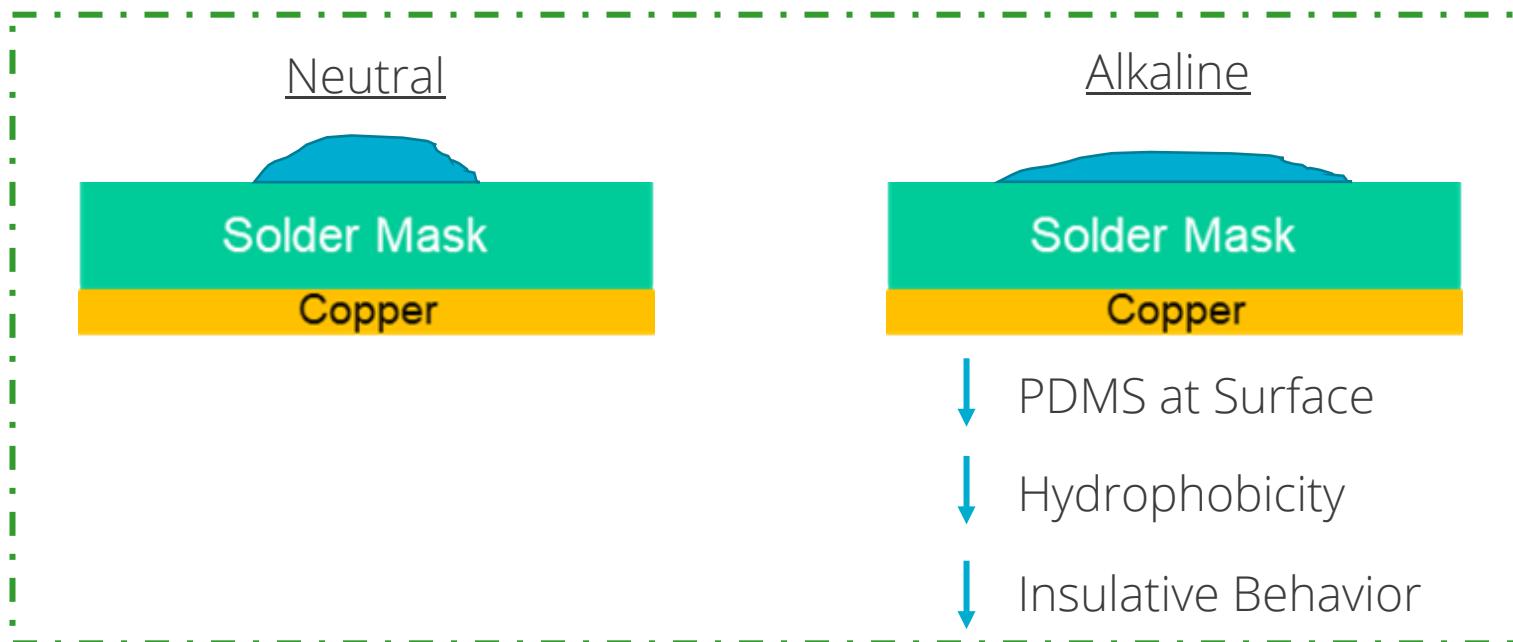
18 20
 $\times 10^{10}$

AC Electrochemical Impedance Spectroscopy

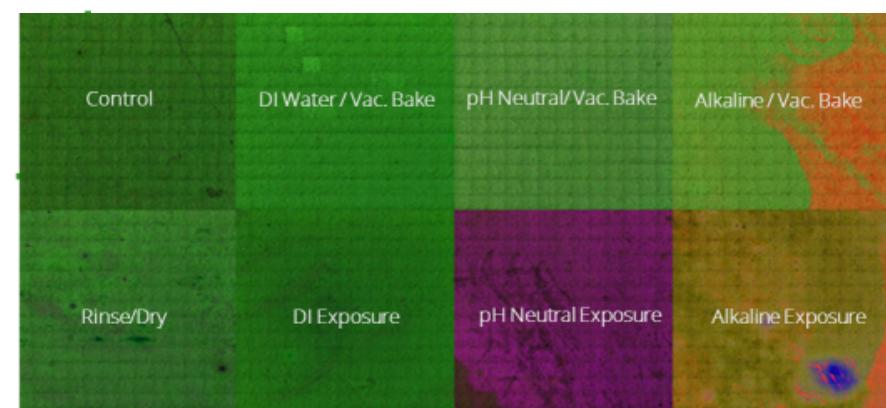
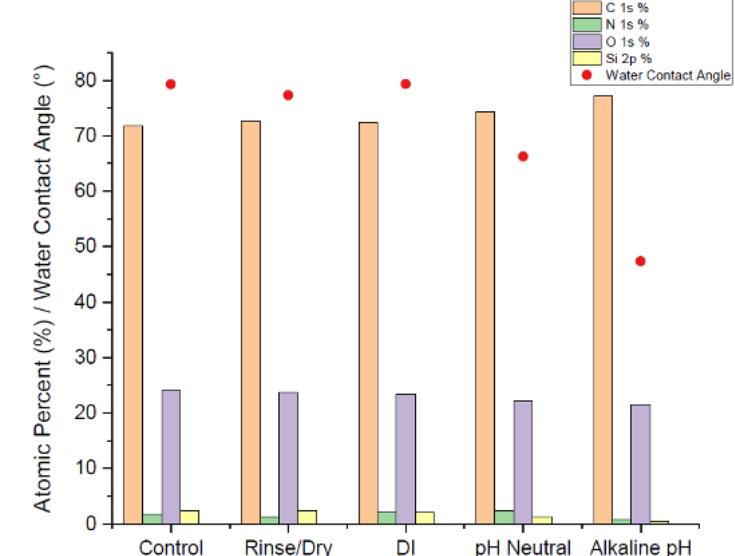
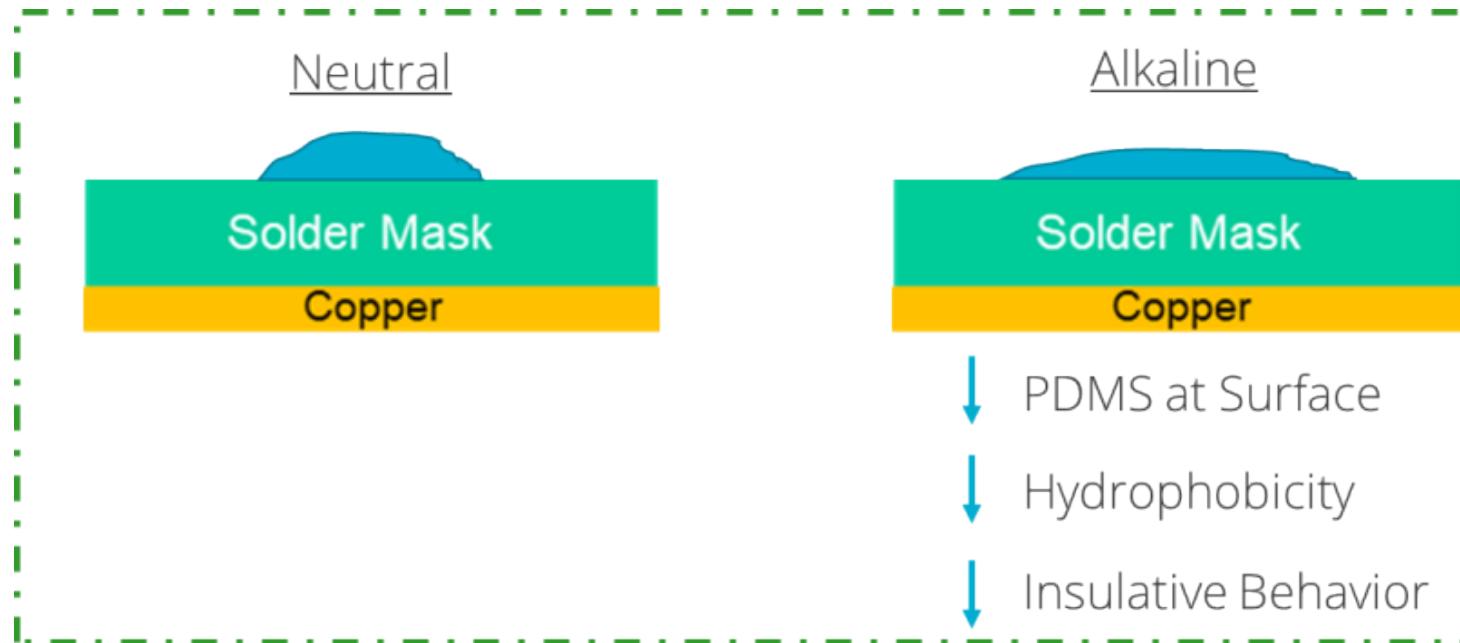


Due to variations in void volume, topography and other 'saturation' factors locally for each sample, difficult to disentangle effect of surface chemistry from other factors in terms of impedance response

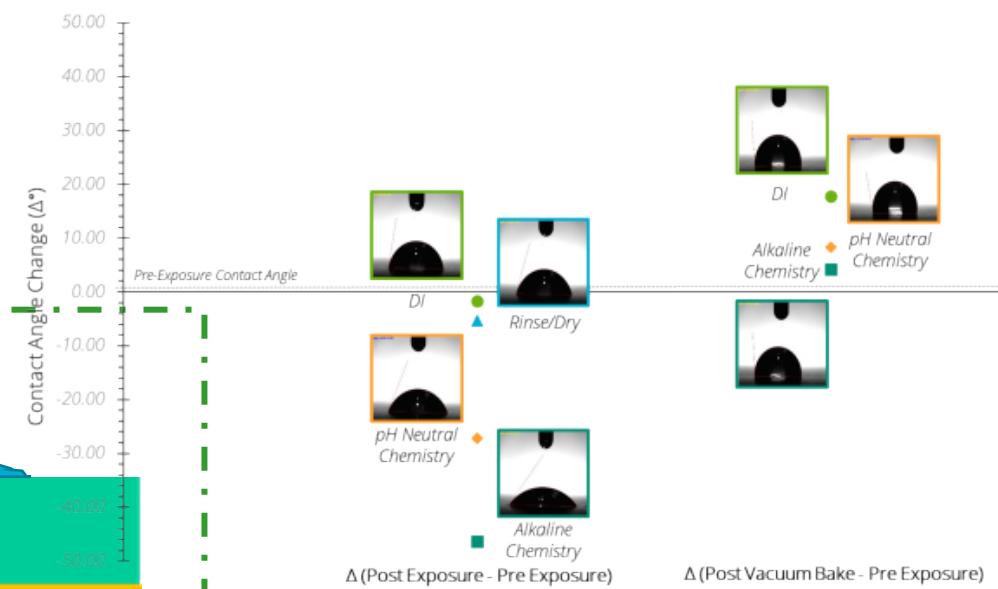
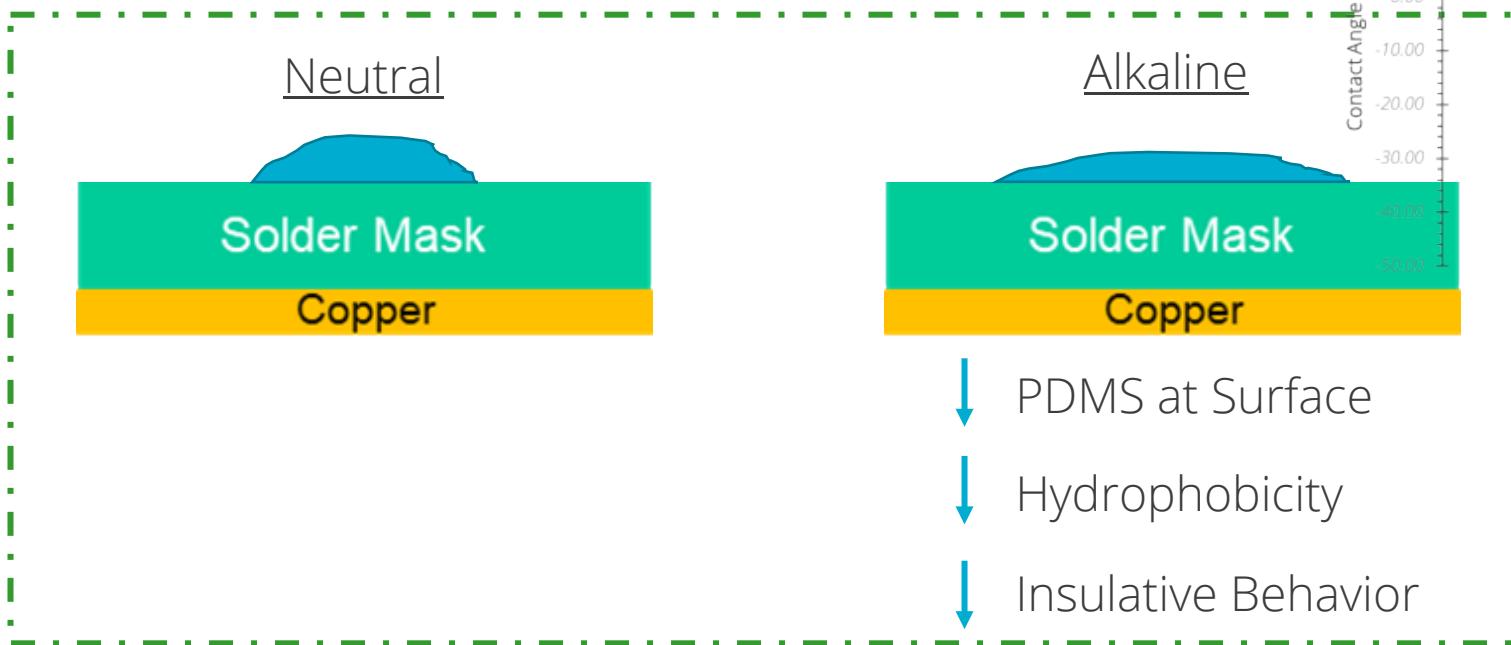
Conclusions



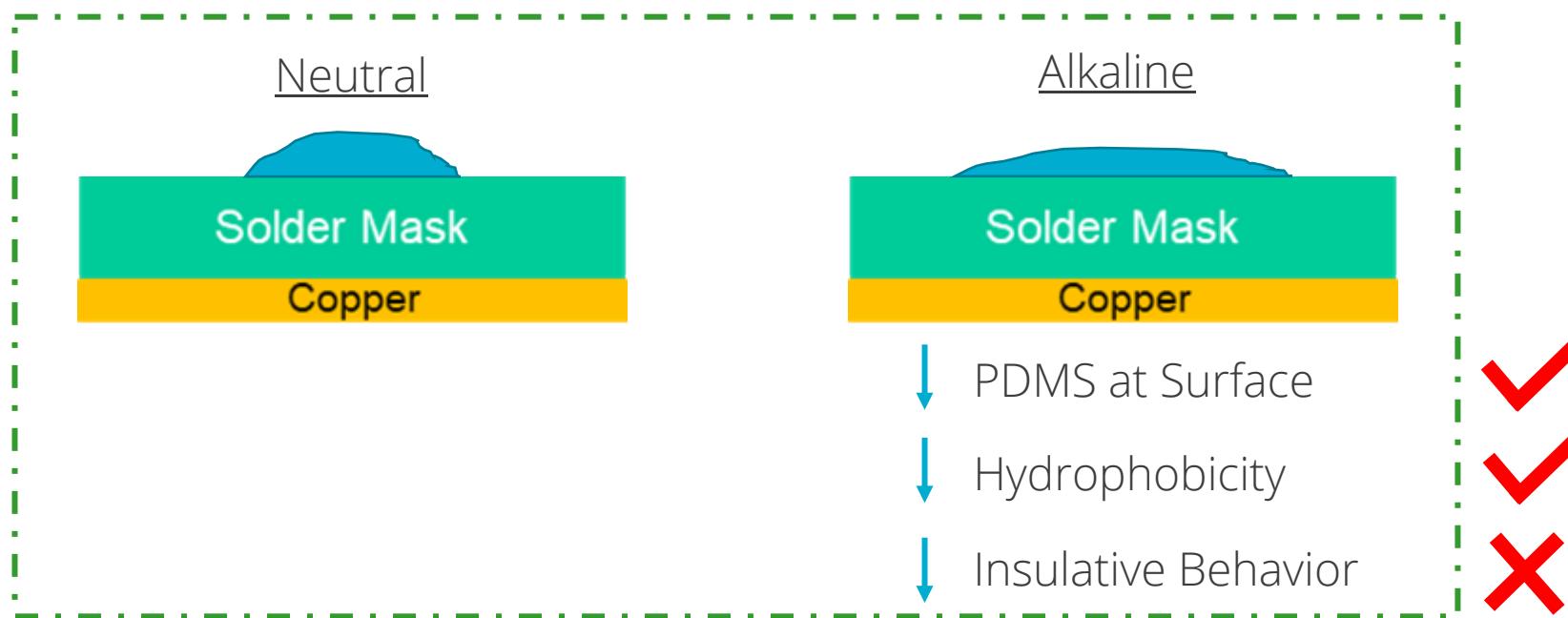
Conclusions



Conclusions



Conclusions



Irreversible Changes to the Surface Chemistry Still Have Downstream Effects (E.G. Adhesion of Coatings) But Still Unclear How Bulk Dielectric Properties Are Affected



Questions?



**Sandia
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SAND2022-